High Current Surface Mount NPN Silicon Switching Transistor for Load Management in Portable Applications

Features

• These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS (T_A = 25°C)

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V _{CEO}	30	Vdc
Collector-Base Voltage	V _{CBO}	50	Vdc
Emitter-Base Voltage	V _{EBO}	5.0	Vdc
Collector Current - Continuous	I _C	1.0	Α
Collector Current - Peak	I _{CM}	2.0	Α

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation (Note 1) @T _A = 25°C Derate above 25°C	P _D	310 2.5	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	403	°C/W
Total Device Dissipation (Note 2) @T _A = 25°C Derate above 25°C	P _D	710 5.7	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	176	°C/W
Total Device Dissipation (Single Pulse < 10 s)	P _{Dsingle}	575	mW
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

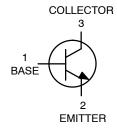
- 1. FR-4 @ Minimum Pad
- 2. FR-4 @ 1.0 X 1.0 inch Pad



ON Semiconductor®

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30 VOLTS, 2.0 AMPERES NPN TRANSISTOR





SOT-23 (TO-236) CASE 318 STYLE 6

MARKING DIAGRAM



N3 = Specific Device Code

M = Date Code*

■ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBT489LT1G	SOT-23 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector – Emitter Breakdown Voltage (I _C = 10 mAdc, I _B = 0)	V _(BR) CEO	30	-	Vdc
Collector-Base Breakdown Voltage (I _C = 0.1 mAdc, I _E = 0)	V _(BR) CBO	50	-	Vdc
Emitter – Base Breakdown Voltage (I _E = 0.1 mAdc, I _C = 0)	V _{(BR)EBO}	5.0	-	Vdc
Collector Cutoff Current (V _{CB} = 30 Vdc, I _E = 0)	Ісво	-	0.1	μAdc
Collector-Emitter Cutoff Current (V _{CES} = 30 Vdc)	I _{CES}	-	0.1	μAdc
Emitter Cutoff Current (V _{EB} = 4.0 Vdc)	I _{EBO}	-	0.1	μAdc
ON CHARACTERISTICS				
DC Current Gain (Note 3) ($I_C = 50$ mA, $V_{CE} = 5.0$ V) ($I_C = 0.5$ A, $V_{CE} = 5.0$ V) ($I_C = 1.0$ A, $V_{CE} = 5.0$ V)	h _{FE}	300 300 200	- 900 -	
Collector – Emitter Saturation Voltage (Note 3) ($I_C = 1.0 \text{ A}, I_B = 100 \text{ mA}$) ($I_C = 0.5 \text{ A}, I_B = 50 \text{ mA}$) ($I_C = 0.1 \text{ A}, I_B = 1.0 \text{ mA}$)	V _{CE(sat)}	- - -	0.200 0.125 0.075	V
Base – Emitter Saturation Voltage (Note 3) $(I_C = 1.0 \text{ A}, I_B = 0.1 \text{ A})$	V _{BE(sat)}	-	1.1	V
Base – Emitter Turn–on Voltage (Note 3) (I _C = 1.0 mA, V _{CE} = 2.0 V)	V _{BE(on)}	-	1.1	V
Cutoff Frequency ($I_C = 100 \text{ mA}$, $V_{CE} = 5.0 \text{ V}$, $f = 100 \text{ MHz}$	f _T	100	-	MHz
Output Capacitance (f = 1.0 MHz)	C _{obo}	-	15	pF

^{3.} Pulsed Condition: Pulse Width = 300 µsec, Duty Cycle ≤ 2%

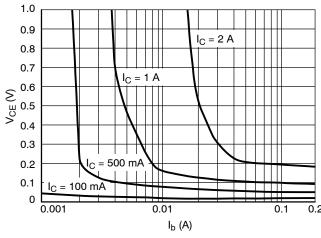


Figure 1. V_{CE} versus I_b

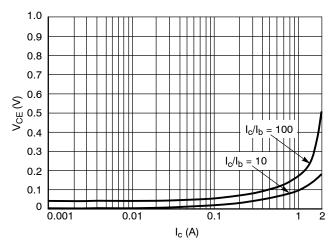


Figure 2. V_{CE} versus I_c

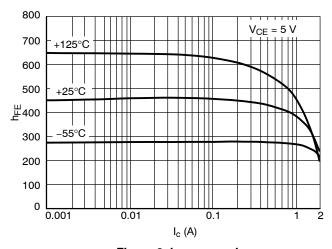


Figure 3. h_{FE} versus I_c

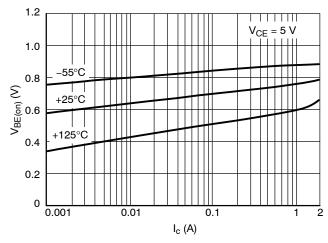


Figure 4. V_{BE(on)} versus I_c

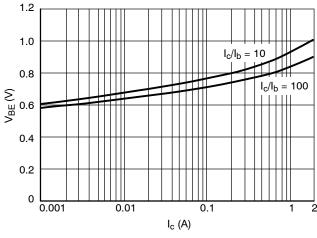


Figure 5. $V_{BE(sat)}$ versus I_c

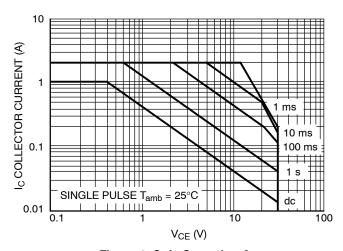


Figure 6. Safe Operating Area

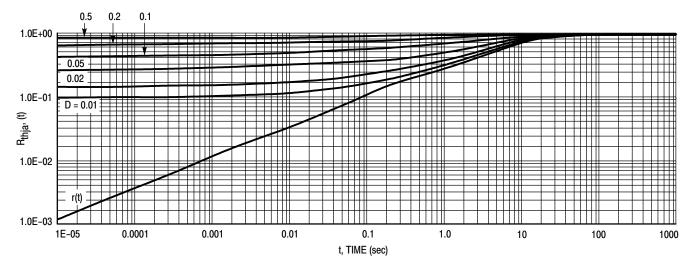
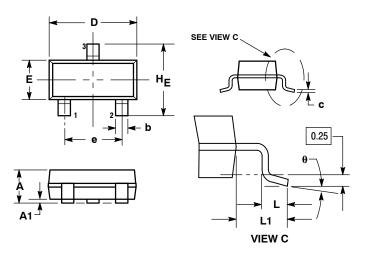


Figure 7. Normalized Thermal Response

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN**



NOTES

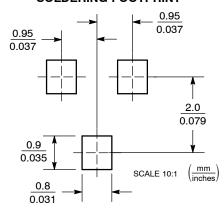
- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6: PIN 1. BASE

EMITTER 2. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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